



BC846BLP4

65V NPN SMALL SIGNAL SURFACE MOUNT TRANSISTOR

Features

- Low Collector-Emitter Saturation Voltage, V_{CE(SAT)}
- Ultra-Small Leadless Surface Mount Package
- Totally Lead-Free & Fully RoHS Compliant (Note 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: X2-DFN1006-3
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu, Solderable per MIL-STD-202, Method 208 @
- Weight: 0.0009 grams (Approximate)

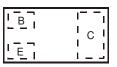
X2-DFN1006-3



Bottom View



Device Symbol



Top View Device Schematic

Ordering Information (Note 4)

Part Number	Marking	Reel Size (in)	Tape Width (mm)	Quantity per Reel
BC846BLP4-7B	3S	7	8	10,000
Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.				

No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.</p>

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



3S = Product Type Marking Code

Top View Bar Denotes Base and Emitter Side



Maximum Ratings (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	80	V
Collector-Emitter Voltage	V _{CEO}	65	V
Emitter-Base Voltage	V _{EBO}	6	V
Collector Current - Continuous	Ic	100	mA
Peak Collector Current	I _{CM}	200	mA
Peak Emitter Current	I _{EM}	200	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit		
Power Dissipation	(Note 5)	P	0.46	W	
	(Note 6)	- P _D	1		
Thermal Resistance, Junction to Ambient	(Note 5)	В	272	°C/W	
	(Note 6)	− R _{θJA}	120	C/ W	
Thermal Resistance, Junction to Leads (Note 7)		$R_{ extsf{ heta}JL}$	110	°C/W	
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C		

ESD Ratings (Note 8)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	200	V	В

Notes: 5. For a device surface mounted on minimum recommended pad layout FR-4 PCB with single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition. The entire exposed collector pad is attached to the heatsink.

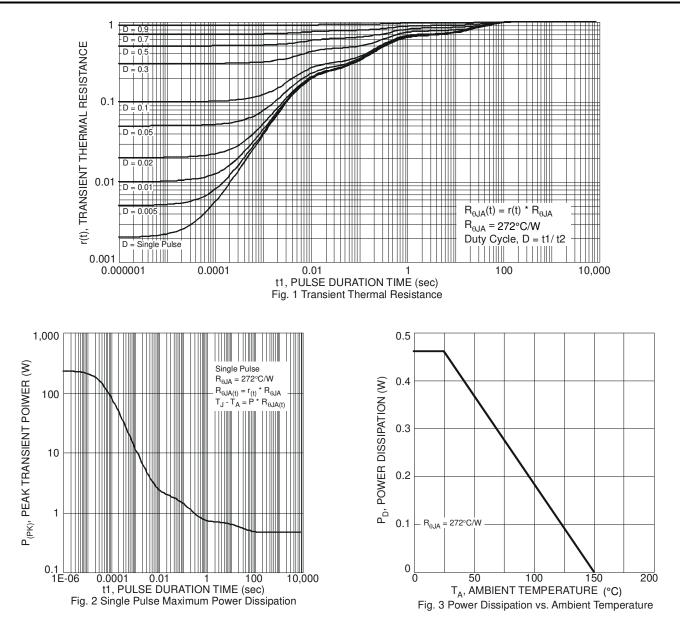
6. Same as Note 5, except device is surface mounted on 25mm X 25mm collector pad heatsink with 1oz copper.

7. Thermal resistance from junction to solder-point (at the end of the collector lead).

8. Refer to JEDEC specification JESD22-A114 and JESD22-A115.



Thermal Characteristics





Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

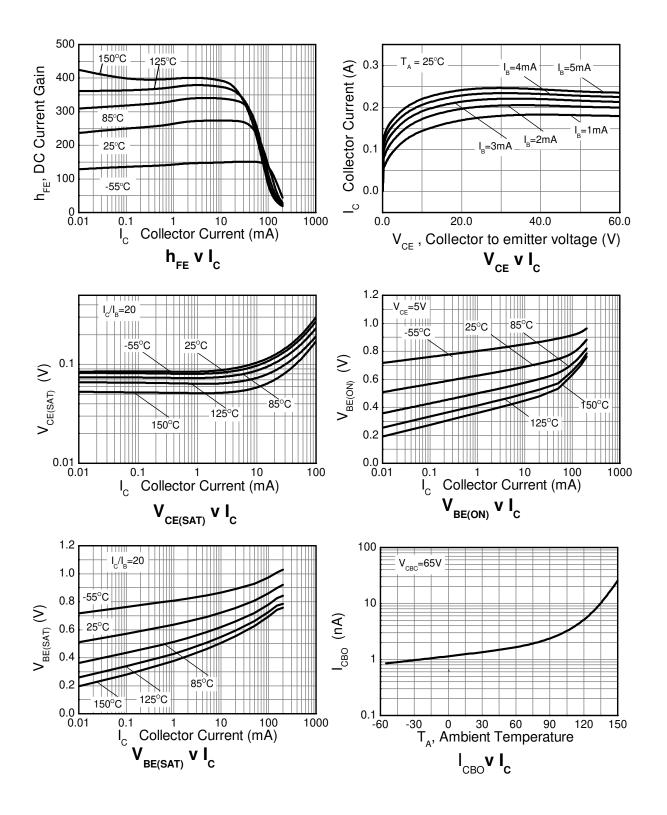
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Collector-Base Breakdown Voltage	BV _{CBO}	80	_		V	$I_{\rm C} = 100 \mu A, I_{\rm E} = 0$
Collector-Emitter Breakdown Voltage (Note 9)	BV _{CEO}	65	_	_	V	$I_{\rm C} = 10 {\rm mA}, I_{\rm B} = 0$
Emitter-Base Breakdown Voltage	BV _{EBO}	6	_	_	V	$I_E = 100 \mu A, I_C = 0$
Collector Cutoff Current	ICES	_	_	15	nA	$V_{CE} = 65V$
Collector Cutoff Current	I _{CBO}	_	_	15 5.0	nA μA	V _{CB} = 40V V _{CB} = 30V, T _A = +150°C
ON CHARACTERISTICS (Note 9)	1	1		1		
DC Current Gain	h _{FE}	200	270	450	_	$V_{CE} = 5V, I_{C} = 2.0mA$
Collector-Emitter Saturation Voltage	V _{CE(SAT)}	_	90 220	250 600	mV	$I_{\rm C} = 10$ mA, $I_{\rm B} = 0.5$ mA $I_{\rm C} = 100$ mA, $I_{\rm B} = 5.0$ mA
Base-Emitter Saturation Voltage	V _{BE(SAT)}		720 870	900	mV	$I_{C} = 10mA, I_{B} = 0.5mA$ $I_{C} = 100mA, I_{B} = 5.0mA$
Base-Emitter Voltage	V _{BE(ON)}	580 —	650 —	700 770	mV	$V_{CE} = 5V$, $I_C = 2.0mA$ $V_{CE} = 5V$, $I_C = 10mA$
SMALL SIGNAL CHARACTERISTICS (Note 9)	•					·
Input Capacitance	Cibo		6.7		pF	V _{CB} = 5V, f = 1.0MHz
Output Capacitance	C _{obo}		1.76		pF	$V_{CB} = 10V, f = 1.0MHz$
Current Gain-Bandwidth Product	f⊤	100	300	—	MHz	$V_{CE} = 5V, I_C = 10mA, f = 100MHz$
Noise Figure	NF	_	2	10	dB	$\label{eq:VCE} \begin{array}{l} V_{CE} = 5V, \ I_C = 200 \mu A, \ R_S = 2.0 k \Omega, \\ f = 1.0 k Hz, \ \Delta f = 200 Hz \end{array}$
Delay Time	t _D		11.2		ns	N/ 001/
Rise Time	t _R		59.7		ns	$V_{CC} = 30V,$
Storage Time	ts		190.8		ns	I _C = 150mA, I _{B1} = -I _{B2} = 15mA
Fall Time	t _F		108.6		ns	$B_1 = -B_2 = 1000A$

Note: 9. Measured under pulsed conditions. Pulse width \leq 300µs. Duty cycle \leq 2%.



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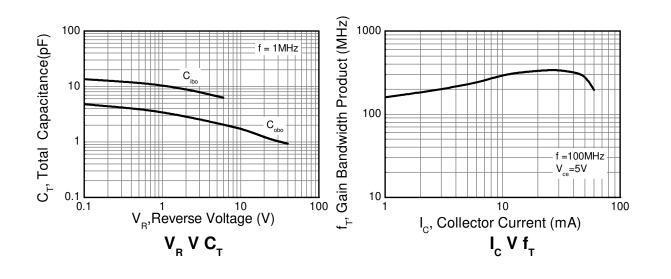
Typical Electrical Characteristics





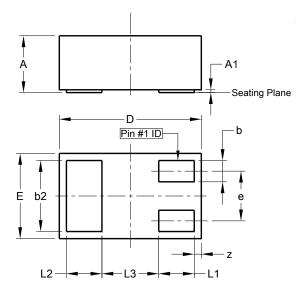
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Typical Electrical Characteristics (Cont.)



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.



X2-DFN1006-3				
Dim	Min	Max	Тур	
Α		0.40		
A1	0.00	0.05	0.03	
b	0.10	0.20	0.15	
b2	0.45	0.55	0.50	
D	0.95	1.05	1.00	
Е	0.55	0.65	0.60	
e	-	-	0.35	
L1	0.20	0.30	0.25	
L2	0.20	0.30	0.25	
L3	-	-	0.40	
Z	0.02	0.08	0.05	
All Dimensions in mm				

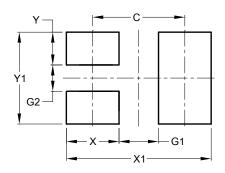
X2-DFN1006-3



Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

X2-DFN1006-3



Dimensions	Value (in mm)			
С	0.70			
G1	0.30			
G2	0.20			
Х	0.40			
X1	1.10			
Ŷ	0.25			
Y1	0.70			

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